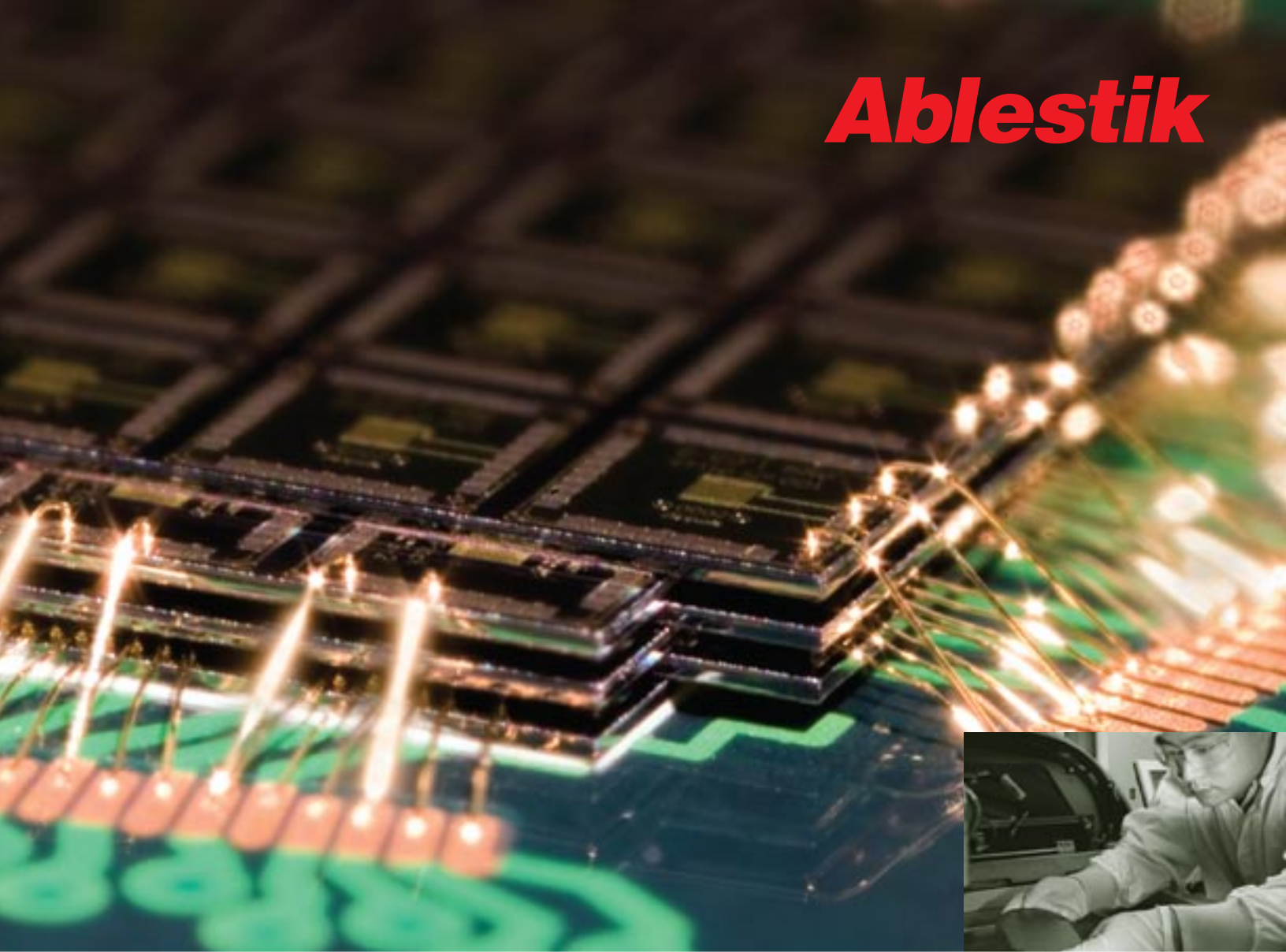


Ablestik



High Performance Dicing Die Attach Films

Enabling Advanced Stacked Die Applications

Henkel



As smaller footprint, higher functioning devices become the norm, stacked die technology will be required to enable the advancement of modern, integrated packages. And, as wafers become thinner and thinner to meet stacking requirements, new materials technology must address the handling and processing challenges of less than 75 micron wafer thicknesses. Henkel's new dicing die attach films offer the solution – materials that combine dicing and die attach functionality into one streamlined product. Available in various thicknesses, these new films deliver outstanding mechanical stability, offer exceptional ease of use, and simplify stacked die processes.

Dicing Die Attach Films

Product	Product Advantages	Film Thickness μm	Application	MRT	Electrical Conductivity	Cure Schedule (Oven)	Warpage m
ATB-S100 Series	Single layer format. Low modulus adhesive for chip-stacking applications. Long thermal budget enables it to apply on multi die stack. Ultra thin thickness is available. Excellent gap filling. Skip curable.	5/10/20/30	DA1, DAX	L2 - 260	Non-Conductive	30 min at 100°C + 30 min at 125°C	Good
ATB-100 Series	Excellent wettability. Easy die pick up. Excellent package reliability. One step lamination.	5/10/30	DA1, DAX	L2 - 260	Non-Conductive	30 min at 100°C + 30 min at 125°C	Very Good
ATB-100A Series	Excellent wettability. Easy die pick up. Excellent package reliability. One step lamination.	10/20	DAX	L2 - 260	Non-Conductive	30 min ramp to 120°C + 60 min at 120°C	Very Good
ATB-100U Series	Fast cure schedule. Can be sampled with UV or non-UV PSA dicing tape. Excellent small die capability.	10/15/20/25/30	DA1	L2 - 260	Non-Conductive	30 min ramp to 120°C + 30 min at 120°C	Very Good
ATB-200 Series	Dual layer format. Very low warpage, excellent for DA1 on PoP. Excellent wettability. Excellent package reliability. Easy pick up. One step lamination.	25/40	DA1	L2 - 260	Non-Conductive	30 min at 100°C + 30 min at 150°C	Excellent
QMI5000 Series	Single layer format. Good bond line thickness control. No bleeding. Dielectric. Skip curable.	10/20	DA1, DAX	L2 - 260	Non-Conductive	N/A	N/A
C100 Series	Electrically conductive, controlled flow suitable for tight geometry leadframe packages. High die shear strength. Good wetting.	15/30	DA1	L2 - 260	Conductive	30 min ramp to 200°C + 60 min at 200°C	N/A
FOW	Film-Over-Wire. Various thickness available.	Various	DAX	L2 - 260	Non-Conductive	-	-

Recommended Products by Application

FBGA



DA1 ATB-S100, QMI5000, (Skip Cure DDF)
ATB-100U, ATB-200 (Cure DDF)

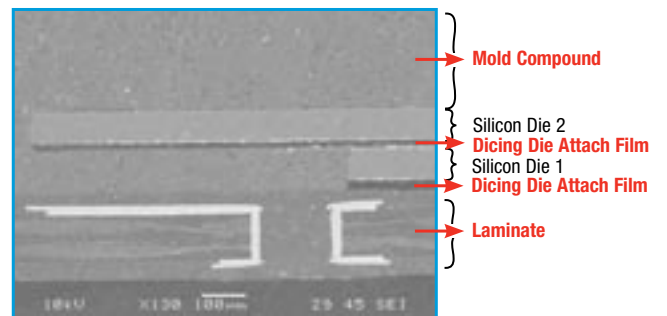
DAX ATB-S100, QMI5000, (Skip Cure DDF)
ATB-100A, ATB-100U (Cure DDF)

Flash Memory Card



DA1 ATB-S100, QMI5000, (Skip Cure DDF)
ATB-100U, ATB-200 (Cure DDF)

TSOP



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Around the Globe.



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